



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-10-27
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD25N10F7	TLDP*OD02R52	A	SHENZHEN B/E	2016-10-27
Amount		UoM	Unit type	ST ECOPACK Grade
330.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
5 - Product(s) is obsolete, no information is available	FALSE
6 - Product(s) is unknown, no information is available	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TLP*OD02R52									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	1.318	mg	supplier	die	Silicon (Si)	7440-21-3		1.262	mg	957511	3824				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.016	mg	12140	48				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	2276	9				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	14416	58				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	759	3				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.013	mg	9863	39				
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	759	3				
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.003	mg	2276	9				
				Leadframe	Copper & its alloys	166.150	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	987975	497430
								supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1986	1000
supplier	alloy	Cobalt (Co)	7440-48-4						0.462	mg	2781	1400				
supplier	metallization	Nickel (Ni)	7440-02-0						1.199	mg	7216	3633				
supplier	metallization	Phosphorus (P)	12185-10-3						0.007	mg	42	21				
Soft solder	Solder	1.795	mg					JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.714	mg	954875	5194
				supplier	solder	Silver (Ag)	7440-22-4		0.045	mg	25070	139				
				supplier	solder	Tin (Sn)	7440-31-5		0.036	mg	20055	109				
				supplier	wire	Aluminium (Al)	7429-90-5		0.456	mg	996068	1382				
Encapsulation	Other Organic Materials	159.234	mg	supplier	wire	Magnesium (Mg)	7439-95-4		0.002	mg	3932	5				
				supplier	mold compound	Silica, vitreous	60676-86-0		139.330	mg	875002	422212				
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bi	EC 413-900-7		6.369	mg	39997	19300				
				supplier	mold compound	Epoxy Resin	25068-38-6		4.777	mg	30000	14476				
				supplier	mold compound	phenol resin	29690-82-2		7.962	mg	50002	24127				
Connections coating	Solder	1.045	mg	supplier	mold compound	Carbon black	1333-86-4		0.796	mg	4999	2412				
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167				